

SOT505-2

TSSOP8, thin shrink small outline package; 8 leads; 0.65 mm pitch; 3 mm x 3 mm x 1.1 mm body

27 August 2025

Package information



1 Package summary

Terminal position code	D (double)
Package type descriptive code	TSSOP8
Package type industry code	TSSOP8
Package style descriptive code	TSSOP (thin shrink small outline package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-01-2002

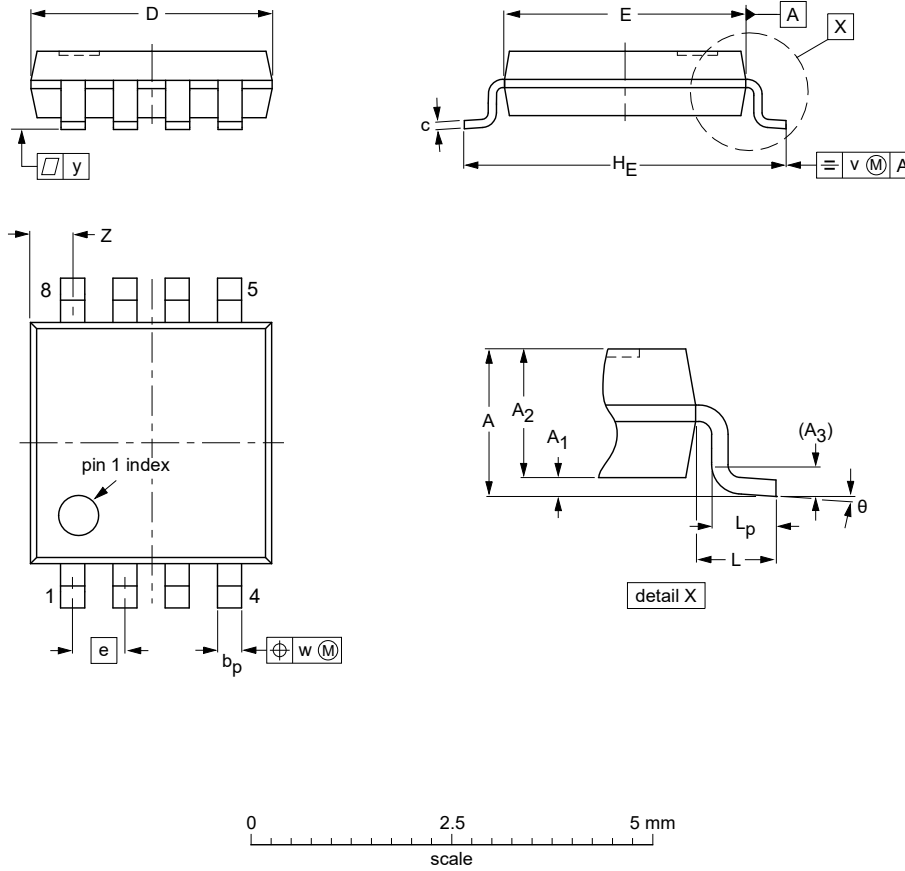
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.9	3	3.1	mm
package width	2.9	3	3.1	mm
seated height	-	1.1	1.1	mm
package height	0.75	0.85	0.95	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	8	-	

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2 Package outline

TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm SOT505-2



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	v	w	y	Z ⁽¹⁾	θ
mm	1.1	0.15 0.00	0.95 0.75	0.25	0.38 0.22	0.18 0.08	3.1 2.9	3.1 2.9	0.65	4.1 3.9	0.5	0.47 0.33	0.2	0.13	0.1	0.70 0.35	8° 0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT505-2		---			02-01-16

Figure 1. Package outline TSSOP8 (SOT505-2)

3 Soldering

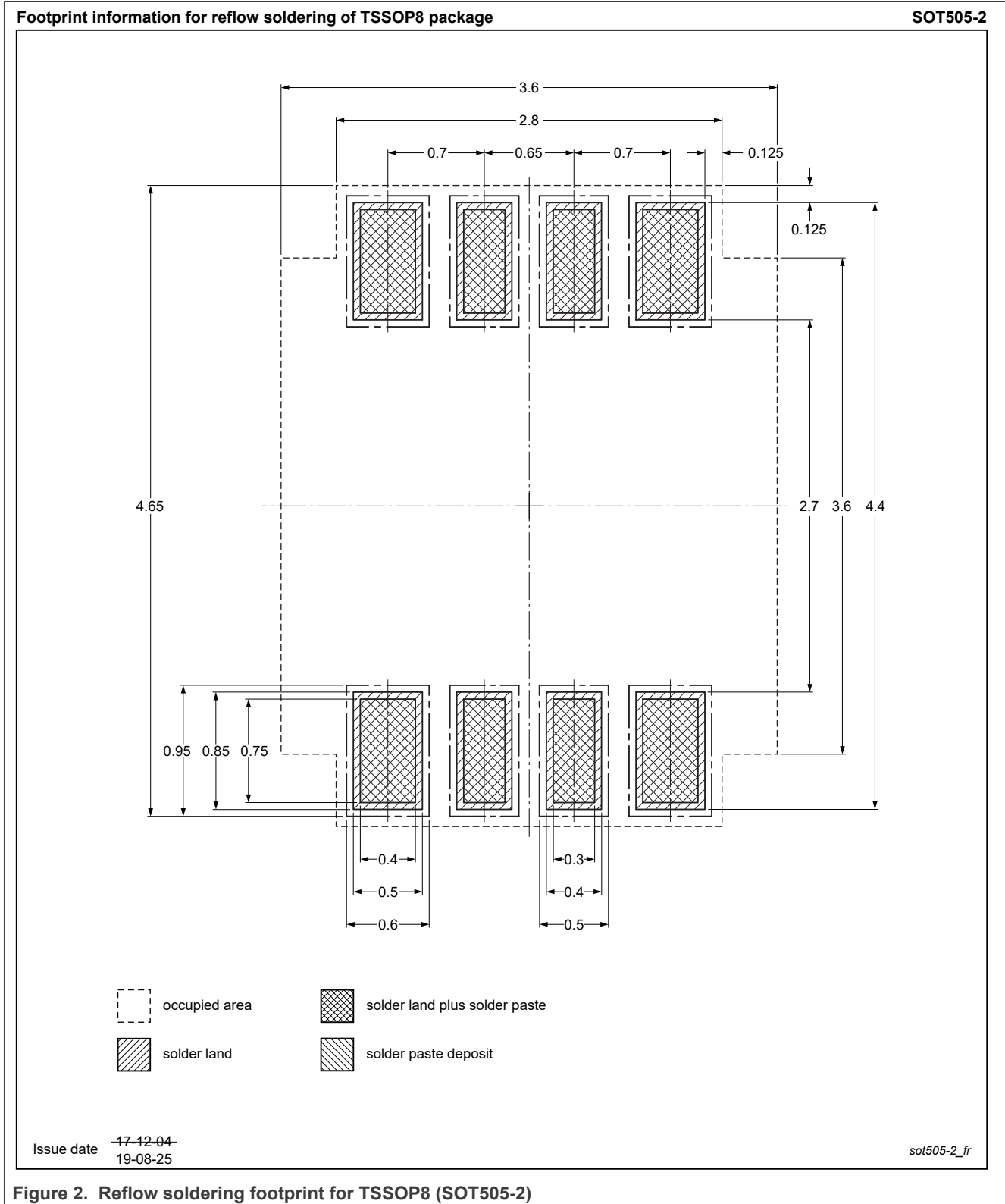


Figure 2. Reflow soldering footprint for TSSOP8 (SOT505-2)

4 Legal information

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